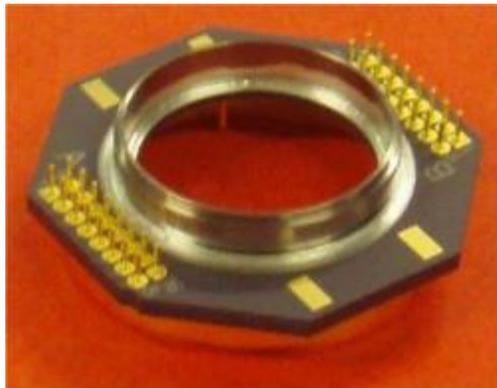


Products for Thermal Imaging



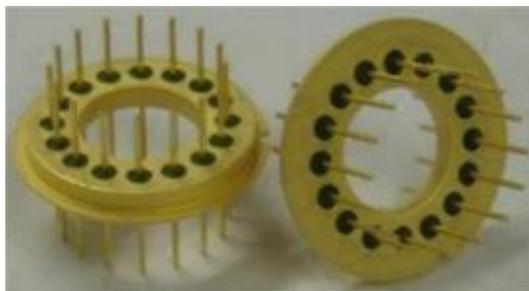
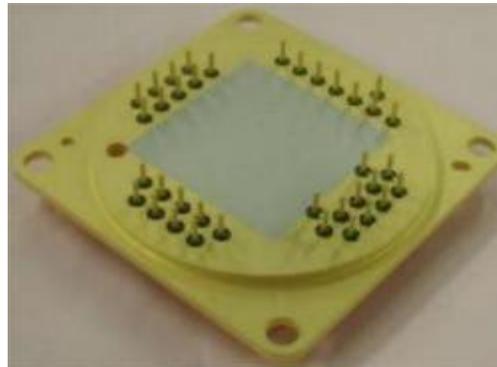
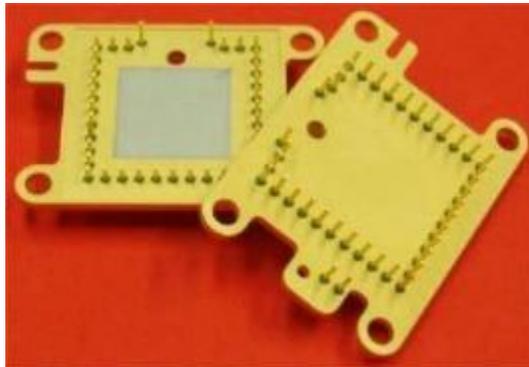
- Development of Brazed Frame w/Ti



UNCOOLED IR : GLASS TO METAL SEAL



- GTMS hermetic packages
- Sealing of different diameters pins depending on the current requirement
- Non-Au plated areas allow customers to braze additional components
- Window assembly : germanium or silicium



Electrical interface :

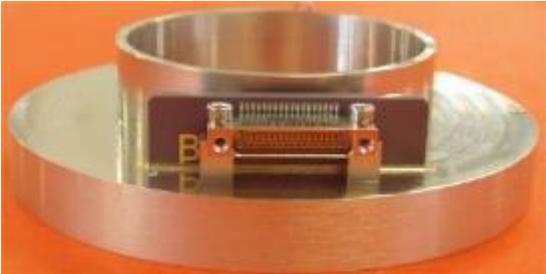


- The ceramic ring could be replaced by a ceramic insert
- Horizontal or vertical brazing
- Electrical I/O's by pins or connectors
- This type of product allows use of a single metal structure and dissociate mechanical and electrical function
- SMT or edge mount connector
- Connector pitch : 2.50mm, 2.00 mm, 1.27 mm, 1.00 mm, 0.635 mm

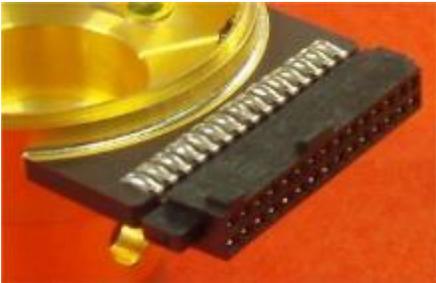


Ø 71 mm
74 i/o 's

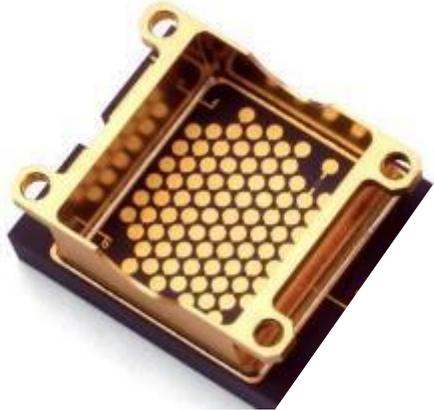
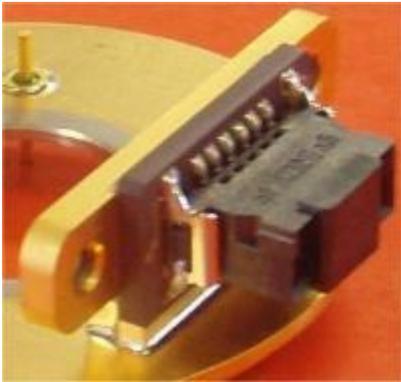
Nano D
Connector
=> pitch :
0.635mm



Connectors

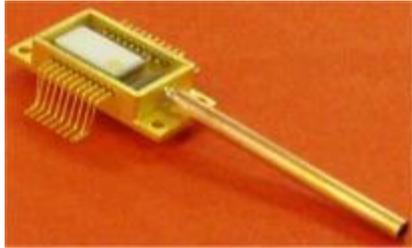
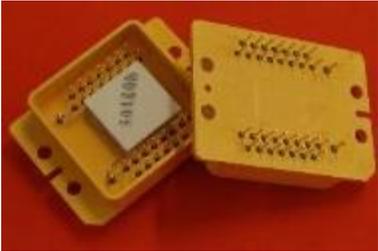
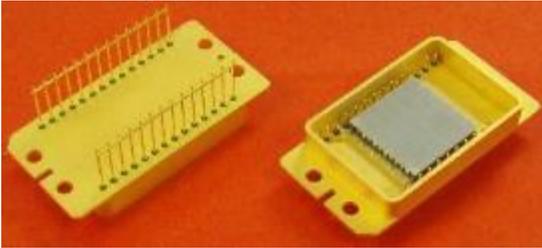


- Different type of connectors could be brazed or assembled to ceramic

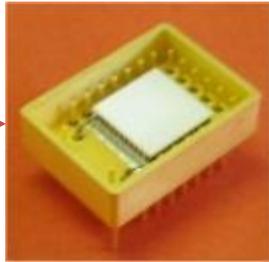


LGA for connector

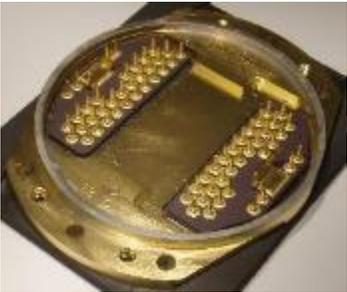
TEC & Getter



- **Special Assemblies**
- TEC Integration
- Brazing of Copper Pumping Tube
- Electrical Welding of Getters & Shields
- Assembly of Substrates



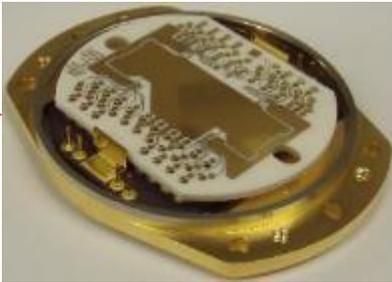
Package



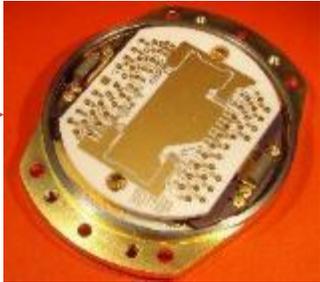
TEC Assembly



Substrate Assembly



Getter Assembly



VARIOUS FORM FACTORS



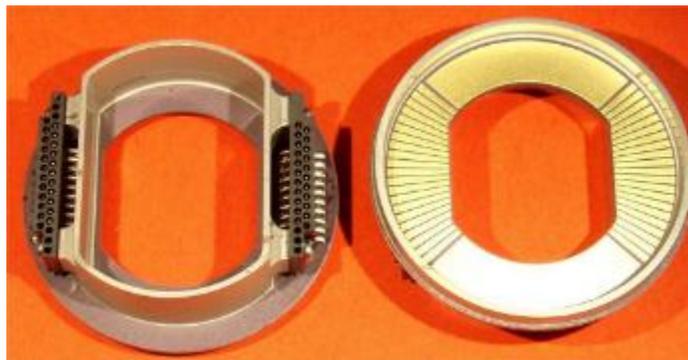
- Lead frame brazed onto pins
- ⇒ horizontal I/O's



- Connectors SMT or Edge Mount.
- Pitch 2.54mm, 2.00mm, 1.27mm, 1.00mm
- Connector "Nano D" Pitch 0.635mm



- Pins for getter welding brazed on the inner diameter of the ceramic ring
- Conductive lines allowing a current of 7A to pass



CERAMIC PACKAGE



- Hermetic package with ceramic base
- Pins for I/O's
- Possibility to integrate elements allowing a pinch-off tube assembly
- Conductive lines allowing a current of 7A
- Integration of getter shielding, TEC, Substrates
- HF lines
- Brazing of metal frame

